TOSHIBA Rectifier Silicon Diffused Type

# CRG07

#### **General Purpose Rectifier Applications**

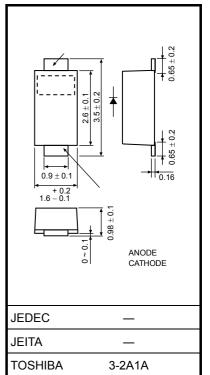
- Average forward current:  $I_F(AV) = 0.7 A$
- Repetitive peak reverse voltage:  $V_{RRM} = 400 V$
- Suitable for compact assembly due to small surface-mount package "S-FLAT<sup>TM</sup>" (Toshiba package name)

### Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit	
Repetitive peak reverse voltage	V <sub>RRM</sub>	100	V	
Average forward current	I <sub>F(AV)</sub>	V) 0.7		
Peak one cycle surge forward current (non-repetitive)	IFSM	15 (50 Hz)	A	
		16.5 (60 Hz)		
Junction temperature	Tj	-40~175(Note2)	ote2) °C	
Storage temperature	T <sub>stg</sub>	-40~175(Note2)	°C	

Note1: Ta = 72°C

Device mounted on a ceramic board Board size:  $50 \text{ mm} \times 50 \text{ mm}$ Soldering size:  $2 \text{ mm} \times 2 \text{ mm}$ Board thickness: 0.64 tHalf Sine Waveform Conduction angle  $180^{\circ}$ 



Weight: 0.013 g (typ.)

- Note2: The definitions of maximum rating condition for both junction temperature and storage temperature range are referred from AEC-Q101.
- Note3: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Electrical Characteristics (Ta = 25°C)**

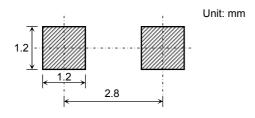
Characteristics	Symbol	Test Condition	Тур.	Max	Unit	
Peak forward voltage	V <sub>FM (1)</sub>	I <sub>FM</sub> = 0.1 A	0.88			
	V <sub>FM (2)</sub>	I <sub>FM</sub> = 0.7 A		1.1	V	
	V <sub>FM (3)</sub>	I <sub>FM</sub> = 1.0 A	1.1	_		
Repetitive peak reverse current	I <sub>RRM</sub>	V <sub>RRM</sub> = Rated	_	10	μA	
Thermal resistance <sup>r</sup> th (j-a)	<b>For</b> (11)	Device mounted on a ceramic board (soldering land: 2 mm × 2 mm)	—	65	°C/W	
	Device mounted on a glass-epoxy board (soldering land: 6 mm $\times$ 6 mm)		130	0/11		

# **TOSHIBA**

## Marking

Abbreviation Code	Part No.		
G7	CRG07		

## Standard Soldering Pad



# **Handling Precaution**

The absolute maximum ratings denote the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The following are the general derating methods that we recommend when you design a circuit with a device.

- VRRM: We recommend that the worst case voltage, including surge voltage, be no greater than 80% of the absolute maximum rating of VRRM for a DC circuit and be no greater than 50% of that of VRRM for an AC circuit. VRRM has a temperature coefficient of 0.1%/ . Take this temperature coefficient into account designing a device at low temperature.
- IF(AV): We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF(AV). Carry out adequate heat design. If you can't design a circuit with excellent heat radiation, set the margin by using an allowable Tamax-IF (AV) curve.

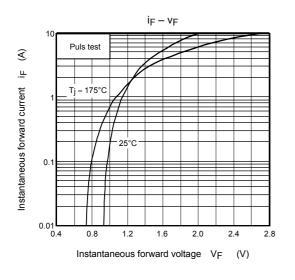
This rating specifies the non-repetitive peak current in one cycle of a 50-Hz sine wave, condition angle 180. Therefore, this is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.

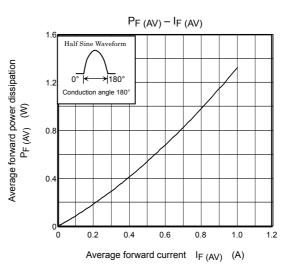
We recommend that a device be used at a Tj of below 140 under the worst load and heat radiation conditions.

Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, design a circuit board and a soldering land size to match the appropriate thermal resistance value.

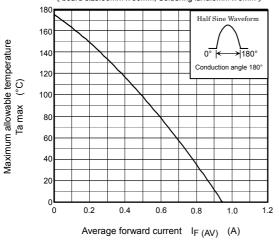
Please refer to the Rectifiers databook for further information.

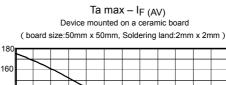
# **TOSHIBA**

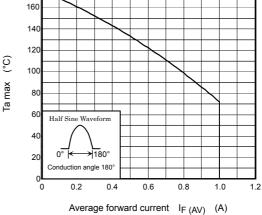


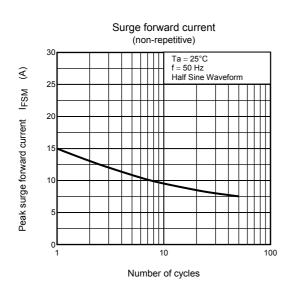


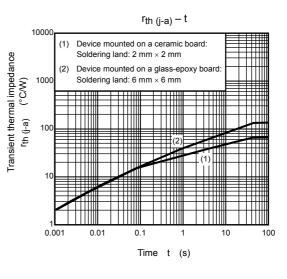
Ta max – I<sub>F (AV)</sub> Device mounted on a glass-epoxy board ( board size:50mm x 50mm, Soldering land:6mm x 6mm )











Maximum allowable temperature

#### **RESTRICTIONS ON PRODUCT USE**

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- The information contained herein is subject to change without notice. 021023\_D
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In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc. 021023\_A

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